

1. (Amended) A solid-state image pickup device comprising:

a substrate;

a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, said solid-state image device pickup element chip being formed on said substrate; and

a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip,

wherein said substrate has a thermal expansion coefficient substantially equal to that of said protection cap, and said substrate and said protection cap are sealed with a sealing resin, so as to form a structure having a hollow space between said solid-state image pickup element chip and said protection cap.

7. (Amended) A solid-state image pickup device comprising:

a substrate;

a solid-state image pickup element chip on which a plurality of solid-state image pickup elements are mounted, said solid-state image device pickup element chip being formed on said substrate; and

a protection cap provided on a light incident side of said solid-state image pickup element chip and adapted to protect said solid-state image pickup element chip,

A2 wherein said substrate is made of the same material as that of said protection cap, and said substrate and protection cap are sealed with a sealing resin, so as to form a substrate having a hollow space between said solid-state image pickup element chip and said protection cap.

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A3 13. (New) The device according to claim 1, wherein on said protection cap, an optical low-pass filter or an infrared filter is formed.

14. (New) The device according to claim 1, wherein at a periphery of said protection cap, a light shielding layer is formed.

15. (New) The device according to claim 1, further comprising a wiring substrate connected electrically to said solid-state image pickup element chip.

16. (New) The device according to claim 15, wherein said wiring substrate is formed of a flexible material.

17. (New) The device according to claim 1, wherein said solid-state image pickup element chip is adhered onto said substrate with a flexible adhesive.

18. (New) The device according to claim 1, wherein a contact-preventive member is provided between each one of said plurality of solid-state image

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pickup elements and said sealing resin so that said sealing resin will not come into contact with said solid-state image pickup elements.

19. (New) The device according to claim 1, wherein said substrate is one of a glass substrate, a ceramic substrate, a metal substrate, a resin substrate, or a substrate formed by stacking two or more of glass, ceramic, metal, and resin substrates.

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cont.  
20. (New) The device according to claim 1, wherein said sealing resin is a resin selected from the group consisting of epoxy, acrylic, and phenol-based resins.

21. (New) The device according to claim 1, further comprising a light-shielding layer, and wherein said solid-state image pickup element chip is formed on said substrate with said light-shielding layer between said substrate and said solid-state image pickup element chip.

22. (New) The device according to claim 7, further comprising a wiring substrate connected electrically to said solid-state image pickup element chip.

23. (New) The device according to claim 22, wherein said wiring substrate is formed of a flexible material.

24. (New) The device according to claim 7, wherein said solid-state image pickup element chip is adhered onto said substrate with a flexible adhesive.

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A3 25. (New) The device according to claim 7, wherein a contact-preventive member is provided between each one of said plurality of solid-state image pickup elements and said sealing resin such that said sealing resin will not come into contact with said solid-state image pickup elements.

26. (New) The device according to claim 7, wherein the substrate is one of a glass substrate, a ceramic substrate, a metal substrate, a resin substrate, or a substrate formed by stacking two or more of glass, ceramic, metal, and resin substrates.

27. (New) The device according to claim 7, wherein said sealing resin is a resin selected from the group consisting of epoxy; acrylic, and phenol-based resins.

28. (New) The device according to claim 7, further comprising a light-shielding layer, and wherein said solid-state image pickup element chip is formed on said substrate with said light-shielding layer between said substrate and said solid-state image pickup element chip.

29. (New) The device according to claim 7, wherein said light-shielding layer is formed of a light shielding and flexible adhesive.